

## Special Issue

# Non-thermal Technologies for Food Processing

### Message from the Guest Editors

The use of emerging non-thermal technologies to produce foods and beverages allows the better retention of the original food flavor/aroma compounds and other thermolabile components, as no heat is employed in the process. In addition, physical processes are a healthy alternative to chemical additives for food preservation. The focus of this Special Issue is technologies such as high-pressure processing, pulsed electric fields, ultrasound, cold plasma, ultraviolet, and pulsed light. Studies may include the effects of processes on food composition, nutrients, structure, and other quality factors, and also microbial and enzyme inactivation. Submissions comparing these technologies alone or combined with heat with conventional thermal processes in terms of cost, safety, energy consumption, effects on quality, scale-up, etc., are also welcome.

### Guest Editors

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### Deadline for manuscript submissions

closed (20 May 2023)



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As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal *Applied Sciences* has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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### Editor-in-Chief

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